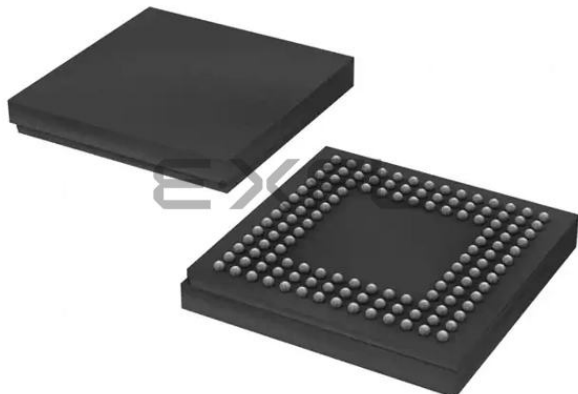




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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Active
Programmable Type	In System Programmable
Delay Time tpd(1) Max	6.7 ns
Voltage Supply - Internal	1.7V ~ 1.9V
Number of Logic Elements/Blocks	16
Number of Macrocells	256
Number of Gates	6000
Number of I/O	106
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	132-TFBGA, CSPBGA
Supplier Device Package	132-CSPBGA (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2c256-7cp132i

By mapping a signal to the DataGATE function, lower power can be achieved due to reduction in signal switching.

Another feature that eases voltage translation is I/O banking. Two I/O banks are available on the CoolRunner-II 256 macrocell device that permit easy interfacing to 3.3V, 2.5V, 1.8V, and 1.5V devices.

The CoolRunner-II 256 macrocell CPLD is I/O compatible with various I/O standards (see [Table 1](#)). This device is also 1.5V I/O compatible with the use of Schmitt-trigger inputs.

RealDigital Design Technology

Xilinx CoolRunner-II CPLDs are fabricated on a 0.18 micron process technology which is derived from leading edge FPGA product development. CoolRunner-II CPLDs employ RealDigital, a design technique that makes use of CMOS technology in both the fabrication and design methodology. RealDigital design technology employs a cascade of CMOS gates to implement sum of products instead of traditional sense amplifier methodology. Due to this technology, Xilinx CoolRunner-II CPLDs achieve both high-performance and low power operation.

Supported I/O Standards

The CoolRunner-II 256 macrocell features LVCMOS, LVTTTL, SSTL and HSTL I/O implementations. See [Table 1](#)

for I/O standard voltages. The LVTTTL I/O standard is a general purpose EIA/JEDEC standard for 3.3V applications that use an LVTTTL input buffer and Push-Pull output buffer. The LVCMOS standard is used in 3.3V, 2.5V, 1.8V applications. Both HSTL and SSTL I/O standards make use of a V_{REF} pin for JEDEC compliance. CoolRunner-II CPLDs are also 1.5V I/O compatible with the use of Schmitt-trigger inputs

Table 1: I/O Standards for XC2C256⁽¹⁾

IOSTANDARD Attribute	Output V_{CCIO}	Input V_{CCIO}	Input V_{REF}	Board Termination Voltage V_{TT}
LVTTTL	3.3	3.3	N/A	N/A
LVCMOS33	3.3	3.3	N/A	N/A
LVCMOS25	2.5	2.5	N/A	N/A
LVCMOS18	1.8	1.8	N/A	N/A
LVCMOS15 ⁽²⁾	1.5	1.5	N/A	N/A
HSTL_1	1.5	1.5	0.75	0.75
SSTL2_1	2.5	2.5	1.25	1.25
SSTL3_1	3.3	3.3	1.5	1.5

(1) For information on V_{ref} , see [XAPP399](#).

(2) LVCMOS15 requires Schmitt-trigger inputs.

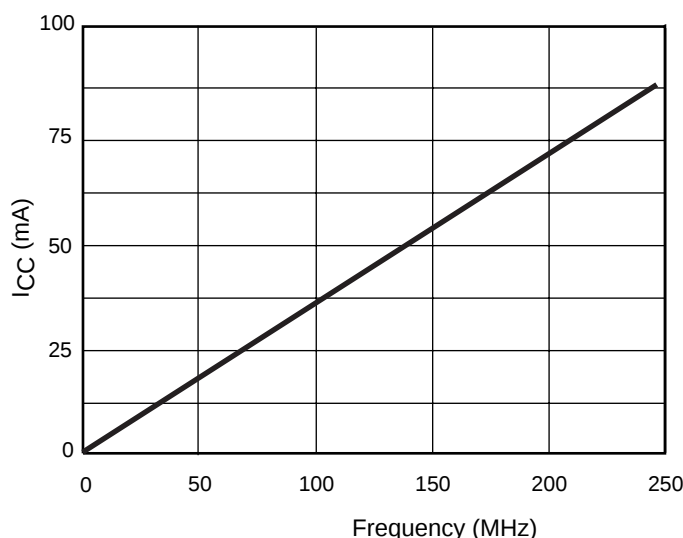


Figure 1: I_{CC} vs Frequency

Table 2: I_{CC} vs Frequency (LVCMOS 1.8V $T_A = 25^\circ\text{C}$)⁽¹⁾

	Frequency (MHz)										
	0	30	50	70	100	120	150	170	190	220	240
Typical I_{CC} (mA)	0.021	11.68	19.40	27.01	38.18	45.54	56.32	63.37	70.40	80.90	88.03

Notes:

- 16-bit up/down, resettable binary counter (one counter per function block).

Absolute Maximum Ratings

Symbol	Description	Value	Units
V_{CC}	Supply voltage relative to ground	–0.5 to 2.0	V
V_{CCIO}	Supply voltage for output drivers	–0.5 to 4.0	V
$V_{JTAG}^{(2)}$	JTAG input voltage limits	–0.5 to 4.0	V
V_{CCAUX}	JTAG input supply voltage	–0.5 to 4.0	V
$V_{IN}^{(1)}$	Input voltage relative to ground	–0.5 to 4.0	V
$V_{TS}^{(1)}$	Voltage applied to 3-state output	–0.5 to 4.0	V
$T_{STG}^{(3)}$	Storage Temperature (ambient)	–65 to +150	°C
T_J	Junction Temperature	+150	°C

Notes:

- Maximum DC undershoot below GND must be limited to either 0.5V or 10 mA, whichever is easiest to achieve. During transitions, the device pins may undershoot to –2.0V or overshoot to +4.5V, provided this over or undershoot lasts less than 10 ns and with the forcing current being limited to 200 mA.
- Valid over commercial temperature range.
- For soldering guidelines and thermal considerations, see the [Device Packaging](#) information on the Xilinx website. For Pb free packages, see [XAPP427](#).

Recommended Operating Conditions

Symbol	Parameter		Min	Max	Units
V _{CC}	Supply voltage for internal logic and input buffers	Commercial T _A = 0°C to +70°C	1.7	1.9	V
		Industrial T _A = −40°C to +85°C	1.7	1.9	V
V _{CCIO}	Supply voltage for output drivers @ 3.3V operation		3.0	3.6	V
	Supply voltage for output drivers @ 2.5V operation		2.3	2.7	V
	Supply voltage for output drivers @ 1.8V operation		1.7	1.9	V
	Supply voltage for output drivers @ 1.5V operation		1.4	1.6	V
V _{CCAUX}	JTAG programming		1.7	3.6	V

DC Electrical Characteristics (Over Recommended Operating Conditions)

Symbol	Parameter	Test Conditions	Typical	Max.	Units
I_{CCSB}	Standby current Commercial	$V_{CC} = 1.9\text{V}$, $V_{CCIO} = 3.6\text{V}$	33	150	μA
I_{CCSB}	Standby current Industrial	$V_{CC} = 1.9\text{V}$, $V_{CCIO} = 3.6\text{V}$	54	300	μA
I_{CC}	Dynamic current	$f = 1\text{ MHz}$	-	410	μA
		$f = 50\text{ MHz}$	-	27	mA
C_{JTAG}	JTAG input capacitance	$f = 1\text{ MHz}$	-	10	pF
C_{CLK}	Global clock input capacitance	$f = 1\text{ MHz}$	-	12	pF
C_{IO}	I/O capacitance	$f = 1\text{ MHz}$	-	10	pF
$I_{IL}^{(2)}$	Input leakage current	$V_{IN} = 0\text{V}$ or V_{CCIO} to 3.9V	-	+/-1	μA
$I_{IH}^{(2)}$	I/O High-Z leakage	$V_{IN} = 0\text{V}$ or V_{CCIO} to 3.9V	-	+/-1	μA

Notes:

- 16-bit up/down, resettable binary counter (one counter per function block) tested at $V_{CC} = V_{CCIO} = 1.9\text{V}$
- See Quality and Reliability section of the CoolRunner-II family data sheet

LVC MOS 3.3V and LV TTL 3.3V DC Voltage Specifications

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V_{CCIO}	Input source voltage	-	3.0	3.6	V
V_{IH}	High level input voltage	-	2	3.9	V
V_{IL}	Low level input voltage	-	-0.3	0.8	V
V_{OH}	High level output voltage	$I_{OH} = -8\text{ mA}, V_{CCIO} = 3\text{V}$	$V_{CCIO} - 0.4\text{V}$	-	V
		$I_{OH} = -0.1\text{ mA}, V_{CCIO} = 3\text{V}$	$V_{CCIO} - 0.2\text{V}$	-	V
V_{OL}	Low level output voltage	$I_{OL} = 8\text{ mA}, V_{CCIO} = 3\text{V}$	-	0.4	V
		$I_{OL} = 0.1\text{ mA}, V_{CCIO} = 3\text{V}$	-	0.2	V

LVC MOS 2.5V DC Voltage Specifications

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V_{CCIO}	Input source voltage	-	2.3	2.7	V
V_{IH}	High level input voltage	-	1.7	$V_{CCIO} + 0.3^{(1)}$	V
V_{IL}	Low level input voltage	-	-0.3	0.7	V
V_{OH}	High level output voltage	$I_{OH} = -8\text{ mA}, V_{CCIO} = 2.3\text{V}$	$V_{CCIO} - 0.4\text{V}$	-	V
		$I_{OH} = -0.1\text{ mA}, V_{CCIO} = 2.3\text{V}$	$V_{CCIO} - 0.2\text{V}$	-	V
V_{OL}	Low level output voltage	$I_{OL} = 8\text{ mA}, V_{CCIO} = 2.3\text{V}$	-	0.4	V
		$I_{OL} = 0.1\text{ mA}, V_{CCIO} = 2.3\text{V}$	-	0.2	V

(1) The V_{IH} Max value represents the JEDEC specification for LVC MOS25. The CoolRunner-II input buffer can tolerate up to 3.9V without physical damage.

LVC MOS 1.8V DC Voltage Specifications

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V_{CCIO}	Input source voltage	-	1.7	1.9	V
V_{IH}	High level input voltage	-	$0.65 \times V_{CCIO}$	$V_{CCIO} + 0.3^{(1)}$	V
V_{IL}	Low level input voltage	-	-0.3	$0.35 \times V_{CCIO}$	V
V_{OH}	High level output voltage	$I_{OH} = -8\text{ mA}, V_{CCIO} = 1.7\text{V}$	$V_{CCIO} - 0.45$	-	V
		$I_{OH} = -0.1\text{ mA}, V_{CCIO} = 1.7\text{V}$	$V_{CCIO} - 0.2$	-	V
V_{OL}	Low level output voltage	$I_{OL} = 8\text{ mA}, V_{CCIO} = 1.7\text{V}$	-	0.45	V
		$I_{OL} = 0.1\text{ mA}, V_{CCIO} = 1.7\text{V}$	-	0.2	V

(1) The V_{IH} Max value represents the JEDEC specification for LVC MOS18. The CoolRunner-II input buffer can tolerate up to 3.9V without physical damage.

LVC MOS 1.5V DC Voltage Specifications⁽¹⁾

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V_{CCIO}	Input source voltage	-	1.4	1.6	V
V_{T+}	Input hysteresis threshold voltage	-	$0.5 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	V
V_{T-}		-	$0.2 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	V

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V_{OH}	High level output voltage	$I_{OH} = -8 \text{ mA}, V_{CCIO} = 1.4\text{V}$	$V_{CCIO} - 0.45$	-	V
		$I_{OH} = -0.1 \text{ mA}, V_{CCIO} = 1.4\text{V}$	$V_{CCIO} - 0.2$	-	V
V_{OL}	Low level output voltage	$I_{OL} = 8 \text{ mA}, V_{CCIO} = 1.4\text{V}$	-	0.4	V
		$I_{OL} = 0.1 \text{ mA}, V_{CCIO} = 1.4\text{V}$	-	0.2	V

Notes:

1. Hysteresis used on 1.5V inputs.

Schmitt Trigger Input DC Voltage Specifications

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V_{CCIO}	Input source voltage	-	1.4	3.9	V
V_{T+}	Input hysteresis threshold voltage	-	$0.5 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	V
V_{T-}		-	$0.2 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	V

SSTL2-1 DC Voltage Specifications

Symbol	Parameter	Test Conditions	Min.	Typ	Max.	Units
V_{CCIO}	Input source voltage	-	2.3	2.5	2.7	V
$V_{REF}^{(1)}$	Input reference voltage	-	1.15	1.25	1.35	V
$V_{TT}^{(2)}$	Termination voltage	-	$V_{REF} - 0.04$	1.25	$V_{REF} + 0.04$	V
V_{IH}	High level input voltage	-	$V_{REF} + 0.18$	-	3.9	V
V_{IL}	Low level input voltage	-	-0.3	-	$V_{REF} - 0.18$	V
V_{OH}	High level output voltage	$I_{OH} = -8 \text{ mA}, V_{CCIO} = 2.3\text{V}$	$V_{CCIO} - 0.62$	-	-	V
V_{OL}	Low level output voltage	$I_{OL} = 8 \text{ mA}, V_{CCIO} = 2.3\text{V}$	-	-	0.54	V

Notes:

1. V_{REF} should track the variations in V_{CCIO} , also peak to peak AC noise on V_{REF} may not exceed $\pm 2\% V_{REF}$
2. V_{TT} of transmitting device must track V_{REF} of receiving devices

SSTL3-1 DC Voltage Specifications

Symbol	Parameter	Test Conditions	Min.	Typ	Max.	Units
V_{CCIO}	Input source voltage	-	3.0	3.3	3.6	V
$V_{REF}^{(1)}$	Input reference voltage	-	1.3	1.5	1.7	V
$V_{TT}^{(2)}$	Termination voltage	-	$V_{REF} - 0.05$	1.5	$V_{REF} + 0.05$	V
V_{IH}	High level input voltage	-	$V_{REF} + 0.2$	-	$V_{CCIO} + 0.3$	V
V_{IL}	Low level input voltage	-	-0.3	-	$V_{REF} - 0.2$	V
V_{OH}	High level output voltage	$I_{OH} = -8 \text{ mA}$, $V_{CCIO} = 3\text{V}$	$V_{CCIO} - 1.1$	-	-	V
V_{OL}	Low level output voltage	$I_{OL} = 8 \text{ mA}$, $V_{CCIO} = 3\text{V}$	-	-	0.7	V

Notes:

- V_{REF} should track the variations in V_{CCIO} , also peak to peak AC noise on V_{REF} may not exceed $\pm 2\% V_{REF}$
- V_{TT} of transmitting device must track V_{REF} of receiving devices

HSTL1 DC Voltage Specifications

Symbol	Parameter	Test Conditions	Min.	Typ	Max.	Units
V_{CCIO}	Input source voltage	-	1.4	1.5	1.6	V
$V_{REF}^{(1)}$	Input reference voltage	-	0.68	0.75	0.90	V
$V_{TT}^{(2)}$	Termination voltage	-	-	$V_{CCIO} \times 0.5$	-	V
V_{IH}	High level input voltage	-	$V_{REF} + 0.1$	-	1.9	V
V_{IL}	Low level input voltage	-	-0.3	-	$V_{REF} - 0.1$	V
V_{OH}	High level output voltage	$I_{OH} = -8 \text{ mA}$, $V_{CCIO} = 1.7\text{V}$	$V_{CCIO} - 0.4$	-	-	V
V_{OL}	Low level output voltage	$I_{OL} = 8 \text{ mA}$, $V_{CCIO} = 1.7\text{V}$	-	-	0.4	V

Notes:

- V_{REF} should track the variations in V_{CCIO} , also peak-to-peak AC noise on V_{REF} may not exceed $\pm 2\% V_{REF}$
- V_{TT} of transmitting device must track V_{REF} of receiving devices

AC Electrical Characteristics Over Recommended Operating Conditions

Symbol	Parameter	-6		-7		Units
		Min.	Max.	Min.	Max.	
T_{PD1}	Propagation delay single p-term	-	5.7	-	6.7	ns
T_{PD2}	Propagation delay OR array	-	6.0	-	7.5	ns
T_{SUD}	Direct input register clock setup time	2.6	-	3.0	-	ns
T_{SU1}	Setup time (single p-term)	2.4	-	2.8	-	ns
T_{SU2}	Setup time (OR array)	2.7	-	3.3	-	ns
T_{HD}	Direct input register hold time	0	-	0	-	ns
T_H	P-term hold time	0	-	0	-	ns
T_{CO}	Clock to output	-	4.5	-	6.0	ns
$F_{TOGGLE}^{(1)}$	Internal toggle rate	-	450	-	300	MHz
$F_{SYSTEM1}^{(2)}$	Maximum system frequency	-	256	-	152	MHz
$F_{SYSTEM2}^{(2)}$	Maximum system frequency	-	238	-	141	MHz
$F_{EXT1}^{(3)}$	Maximum external frequency	-	145	-	114	MHz
$F_{EXT2}^{(3)}$	Maximum external frequency	-	139	-	108	MHz
T_{PSUD}	Direct input register p-term clock setup time	1.3	-	1.7	-	ns

Symbol	Parameter	-6		-7		Units
		Min.	Max.	Min.	Max.	
T_{PSU1}	P-term clock setup time (single p-term)	1.2	-	1.5	-	ns
T_{PSU2}	P-term clock setup time (OR array)	1.5	-	2.0	-	ns
T_{PHD}	Direct input register p-term clock hold time	1.1	-	1.2	-	ns
T_{PH}	P-term clock hold	1.0	-	1.0	-	ns
T_{PCO}	P-term clock to output	-	6.5	-	7.3	ns
T_{OE}/T_{OD}	Global OE to output enable/disable	-	5.6	-	7.0	ns
T_{POE}/T_{POD}	P-term OE to output enable/disable	-	7.3	-	8.0	ns
T_{MOE}/T_{MOD}	Macrocell driven OE to output enable/disable	-	7.4	-	9.9	ns
T_{PAO}	P-term set/reset to output valid	-	7.5	-	8.1	ns
T_{AO}	Global set/reset to output valid	-	5.7	-	7.6	ns
T_{SUEC}	Register clock enable setup time	2.8	-	3.1	-	ns
T_{HEC}	Register clock enable hold time	0	-	0	-	ns
T_{CW}	Global clock pulse width High or Low	1.1	-	1.6	-	ns
T_{PCW}	P-term pulse width High or Low	6.0	-	7.5	-	ns
T_{APRPW}	Asynchronous preset/reset pulse width (High or Low)	6.0	-	7.5	-	ns
T_{DGSU}	Set-up before DataGATE latch assertion	0	-	0	-	ns
T_{DGH}	Hold to DataGATE latch assertion	4.0	-	6.0	-	ns
T_{DGR}	DataGATE recovery to new data	-	8.2	-	9.0	ns
T_{DGW}	DataGATE low pulse width	2.5	-	3.5	-	ns
T_{CDRSU}	CDRST setup time before falling edge GCLK2	1.6	-	2.0	-	ns
T_{CDRH}	Hold time CDRST after falling edge GCLK2	0	-	0	-	ns
$T_{CONFIG}^{(4)}$	Configuration time	-	150	-	150	μ s

Notes:

1. F_{TOGGLE} is the maximum clock frequency to which a T-Flip Flop can reliably toggle (see the CoolRunner-II family data sheet for more information).
2. $F_{SYSTEM1}$ ($1/T_{CYCLE}$) is the internal operating frequency for a device fully populated with one 16-bit counter through one p-term per macrocell while $F_{SYSTEM2}$ is through the OR array.
3. F_{EXT1} ($1/T_{SU1}+T_{CO}$) is the maximum external frequency using one p-term while F_{EXT2} is through the OR array.
4. Typical configuration current during T_{CONFIG} is approximately 7.7 mA.

Internal Timing Parameters

Symbol	Parameter ⁽²⁾	-6		-7		Units
		Min.	Max.	Min.	Max.	
Buffer Delays						
T _{IN}	Input buffer delay	-	2.4	-	2.6	ns
T _{DIN}	Direct data register input delay	-	3.1	-	3.9	ns
T _{GCK}	Global Clock buffer delay	-	1.8	-	2.7	ns
T _{GSR}	Global set/reset buffer delay	-	2.0	-	3.5	ns
T _{GTS}	Global 3-state buffer delay	-	2.1	-	3.0	ns
T _{OUT}	Output buffer delay	-	2.3	-	2.6	ns
T _{EN}	Output buffer enable/disable delay	-	3.5	-	4.0	ns
P-term Delays						
T _{CT}	Control term delay	-	1.1	-	1.4	ns
T _{LOGI1}	Single P-term delay adder	-	0.5	-	1.1	ns
T _{LOGI2}	Multiple P-term delay adder	-	0.3	-	0.5	ns
Macrocell Delay						
T _{PDI}	Input to output valid	-	0.5	-	0.7	ns
T _{SUI}	Setup before clock	1.3	-	1.8	-	ns
T _{HI}	Hold after clock	0	-	0	-	ns
T _{ECSU}	Enable clock setup time	0.8	-	1.8	-	ns
T _{ECHO}	Enable clock hold time	0	-	0	-	ns
T _{COI}	Clock to output valid	-	0.4	-	0.7	ns
T _{AOI}	Set/reset to output valid	-	1.4	-	1.5	ns
T _{CDBL}	Clock doubler delay	-	0	-	0	ns
Feedback Delays						
T _F	Feedback delay	-	1.7	-	3.0	ns
T _{OEM}	Macrocell to global OE delay	-	1.7	-	2.5	ns
I/O Standard Time Adder Delays 1.5V CMOS						
T _{HYS15}	Hysteresis input adder	-	3.0	-	4.0	ns
T _{OUT15}	Output adder	-	0.8	-	1.0	ns
T _{SLEW15}	Output slew rate adder	-	4.0	-	5.0	ns
I/O Standard Time Adder Delays 1.8V CMOS						
T _{HYS18}	Hysteresis input adder	-	2.0	-	3.0	ns
T _{OUT18}	Output adder	-	0	-	0	ns
T _{SLEW}	Output slew rate adder	-	2.0	-	4.0	ns

Internal Timing Parameters (Continued)

Symbol	Parameter ⁽²⁾	-6		-7		Units
		Min.	Max.	Min.	Max.	
I/O Standard Time Adder Delays 2.5V CMOS						
T _{IN25}	Standard input adder	-	0.6	-	0.7	ns
T _{HYS25}	Hysteresis input adder	-	1.5	-	3.0	ns
T _{OUT25}	Output adder	-	0.8	-	1.0	ns
T _{SLEW25}	Output slew rate adder	-	3.0	-	4.0	ns
I/O Standard Time Adder Delays 3.3V CMOS/TTL						
T _{IN33}	Standard input adder	-	0.5	-	0.7	ns
T _{HYS33}	Hysteresis input adder	-	1.2	-	3.0	ns
T _{OUT33}	Output adder	-	1.2	-	1.6	ns
T _{SLEW33}	Output slew rate adder	-	3.0	-	4.0	ns
I/O Standard Time Adder Delays HSTL, SSTL						
SSTL2-1	Input adder to T _{IN} , T _{DIN} , T _{GCK} , T _{GSR} , T _{GTS}	-	0.4	-	1.0	ns
	Output adder to T _{OUT}	-	-0.5	-	0.0	ns
SSTL3-1	Input adder to T _{IN} , T _{DIN} , T _{GCK} , T _{GSR} , T _{GTS}	-	0.4	-	1.0	ns
	Output adder to T _{OUT}	-	-0.5	-	0.0	ns
HSTL-1	Input adder to T _{IN} , T _{DIN} , T _{GCK} , T _{GSR} , T _{GTS}	-	0.6	-	1.0	ns
	Output adder to T _{OUT}	-	0	-	0	ns

Notes:

- 1.5 ns input pin signal rise/fall.

Switching Characteristics

AC Test Circuit

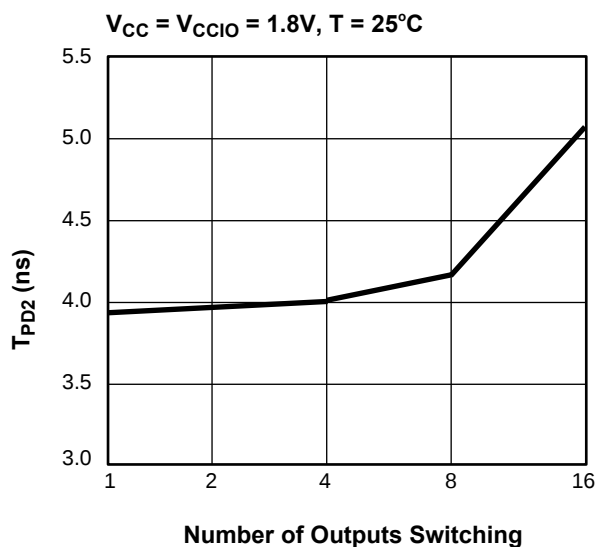
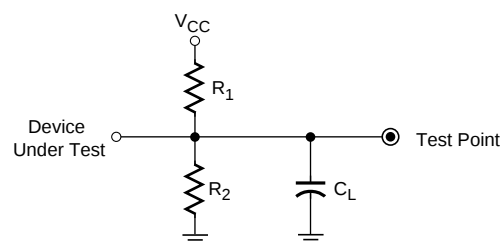


Figure 2: Derating Curve for T_{PD}

DS092_02_092302



Output Type	R_1	R_2	C_L
LVTTL33	268 Ω	235 Ω	35 pF
LVC MOS33	275 Ω	275 Ω	35 pF
LVC MOS25	188 Ω	188 Ω	35 pF
LVC MOS18	112.5 Ω	112.5 Ω	35 pF
LVC MOS15	150 Ω	150 Ω	35 pF

C_L includes test fixtures and probe capacitance.
1.5 nsec maximum rise/fall times on inputs.

Figure 3: AC Load Circuit

DS ACT 08 14 02

Typical I/V Output Curves

The I/V curve illustrates the nominal amount of current that an I/O can source/sink at different voltage levels.

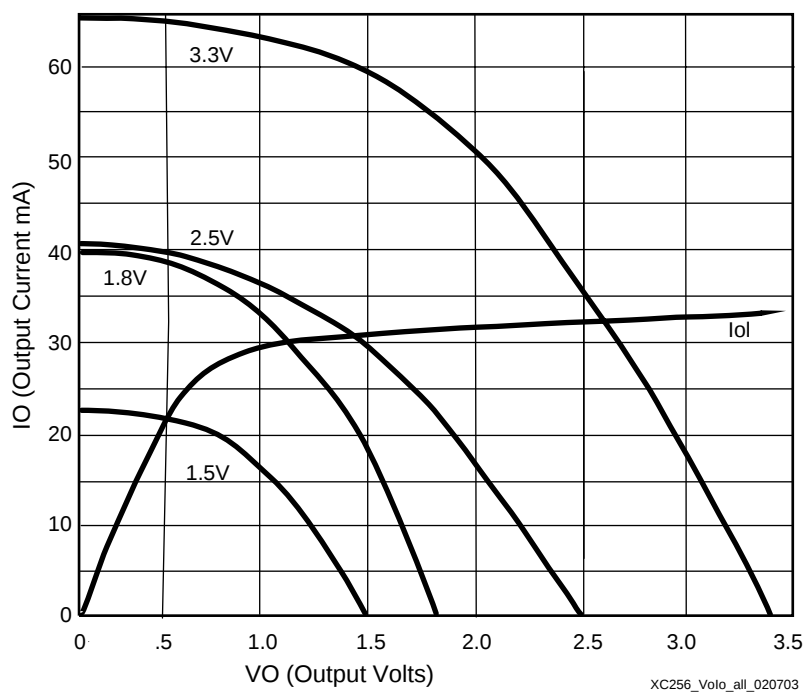


Figure 4: Typical I/V Curve for XC2C256

Pin Descriptions

Function Block	Macro-cell	VQ100	CP132	TQ144	PQ208	FT256	I/O Bank
1	1	-	-	-	2	B3	2
1	2	-	-	-	208	B4	2
1(GSR)	3	99	A3	143	206	C4	2
1	4	-	-	142	205	A2	2
1	5	-	-	-	203	A3	2
1	6	97	B4	140	202	A4	2
1	7	-	-	-	-	-	-
1	8	-	-	-	-	-	-
1	9	-	-	-	-	-	-
1	10	-	-	-	-	-	-
1	11	-	-	-	-	-	-
1	12	96	-	139	201	B5	2
1	13	95	-	138	200	A5	2
1	14	94	A4	137	199	E8	2
1	15	-	-	-	198	B6	2
1	16	-	C5	-	197	C7	2
2(GTS2)	1	1	A1	2	3	D3	2
2	2	-	-	-	4	C3	2
2(GTS3)	3	2	B2	3	5	E3	2
2	4	-	B1	4	6	B2	2
2(GTS0)	5	3	C3	5	7	D4	2
2	6	-	-	-	8	D2	2
2	7	-	-	-	-	-	-
2	8	-	-	-	-	-	-
2	9	-	-	-	-	-	-
2	10	-	-	-	-	-	-
2	11	-	-	-	-	-	-
2(GTS1)	12	4	C2	6	9	E5	2
2	13	-	C1	7	10	B1	2
2	14	6	D2	9	12	E4	2
2	15	7	-	10	14	C1	2
2	16	-	D1	-	-	E2	2

Pin Descriptions (Continued)

Function Block	Macro-cell	VQ100	CP132	TQ144	PQ208	FT256	I/O Bank
3	1	-	-	136	196	A6	2
3	2	-	B5	135	195	D7	2
3	3	-	-	134	194	B7	2
3	4	-	A5	-	193	E9	2
3	5	93	-	133	192	A7	2
3	6		C6		191	D8	2
3	7	-	-	-	-	-	-
3	8	-	-	-	-	-	-
3	9	-	-	-	-	-	-
3	10	-	-	-	-	-	-
3	11	-	-	-	-	-	-
3	12	92	-	-	189	B8	2
3	13	-	B6	-	188	C8	2
3	14	91	A6	132	187	A8	2
3	15	-	C7	-	186	E11	2
3	16	90	B7	131	185	E10	2
4	1	8	E3	11	15	F2	2
4	2	9	-	12	16	F3	2
4	3	10	E2	13	17	G4	2
4	4	-	E1	14	18	G3	2
4	5	11	F3	15	19	F5	2
4	6	12	F2	16	20	G5	2
4	7	-	-	-	-	-	-
4	8	-	-	-	-	-	-
4	9	-	-	-	-	-	-
4	10	-	-	-	-	-	-
4	11	-	-	-	-	-	-
4	12	-	F1	17	21	H2	2
4	13	13	G1	-	22	H4	2
4	14	-	-	18	23	H3	2
4	15	-	-	-	-	H1	2
4	16	-	-	-	25	H5	2

Pin Descriptions (Continued)

Function Block	Macro-cell	VQ100	CP132	TQ144	PQ208	FT256	I/O Bank
5	1	-	L3	-	49	R1	1
5	2	-	-	33	48	N4	1
5	3	-	-	-	47	N2	1
5(GCK1)	4	23	L2	32	46	M3	1
5	5	-	L1	31	45	P1	1
5(GCK0)	6	22	K3	30	44	M2	1
5	7	-	-	-	-	-	-
5	8	-	-	-	-	-	-
5	9	-	-	-	-	-	-
5	10	-	-	-	-	-	-
5	11	-	-	-	-	-	-
5	12	-	-	-	43	L3	1
5	13	-	-	-	41	N1	1
5	14	-	-	28	40	L4	1
5	15	-	-	-	39	M1	1
5	16	-	K1	-	38	L5	1
6	1	-	M1	34	50	N3	1
6 (CDRST)	2	24	M2	35	51	P2	1
6	3	-	-	-	54	P4	1
6(GCK2)	4	27	N2	38	55	P5	1
6	5	-	-	-	56	R2	1
6	6	-	-	-	57	T1	1
6	7	-	-	-	-	-	-
6	8	-	-	-	-	-	-
6	9	-	-	-	-	-	-
6	10	-	-	-	-	-	-
6	11	-	-	-	-	-	-
6(DGE)	12	28	P2	39	58	T2	1
6	13	-	M3	40	60	N5	1
6	14	29	N3	41	61	R4	1
6	15	-	P3	42	62	M5	1
6	16	30	M4	43	63	R5	1

Pin Descriptions (Continued)

Function Block	Macro-cell	VQ100	CP132	TQ144	PQ208	FT256	I/O Bank
7	1	-	-	-	37	K4	1
7	2	-	-	-	36	L2	1
7	3	-	-	-	35	K3	1
7	4	-	-	-	34	L1	1
7	5	19	J2	26	32	K5	1
7	6	18	J1	25	31	K2	1
7	7	-	-	-	-	-	-
7	8	-	-	-	-	-	-
7	9	-	-	-	-	-	-
7	10	-	-	-	-	-	-
7	11	17	H3	24	30	J4	1
7	12	16	H2	23	29	K1	1
7	13	15	H1	22	28	J3	1
7	14	14	G3	21	27	J2	1
7	15	-	G2	20	-	J5	1
7	16	-	-	19	-	J1	1
8	1	-	N4	44	64	R6	1
8	2	-	-	45	65	N6	1
8	3	-	-	46	66	R3	1
8	4	-	-	-	67	M6	1
8	5	-	-	48	69	T3	1
8	6	32	-	49	70	P6	1
8	7	-	-	-	-	-	-
8	8	-	-	-	-	-	-
8	9	-	-	-	-	-	-
8	10	-	-	-	-	-	-
8	11	33	M5	50	71	T4	1
8	12	34	N5	51	72	P7	1
8	13	35	P5	52	73	T5	1
8	14	36	M6	-	74	N7	1
8	15	37	N6	-	75	R7	1
8	16	-	-	-	76	M7	1

Pin Descriptions (Continued)

Function Block	Macro-cell	VQ100	CP132	TQ144	PQ208	FT256	I/O Bank
9	1	78	C12	112	160	B13	2
9	2	79	B12	113	161	B14	2
9	3	-	-	-	162	C13	2
9	4	80	A12	114	163	A15	2
9	5				164	C12	2
9	6	81	C11	115	165	B12	2
9	7	-	-	-	-	-	-
9	8	-	-	-	-	-	-
9	9	-	-	-	-	-	-
9	10	-	-	-	-	-	-
9	11	-	-	-	166	D13	2
9	12	82	B11	116	167	A14	2
9	13	-	-	117	168	E13	2
9	14	-	A11	118	169	A13	2
9	15	-	-	119	170	C11	2
9	16	-	C10	-	171	A12	2
10	1	77	A13	111	159	A16	2
10	2	76	B13	110	158	B15	2
10	3	74	C13	107	155	C14	2
10	4	73	C14	106	154	G11	2
10	5	72	D12	105	153	B16	2
10	6	71	D13	104	152	D15	2
10	7	-	-	-	-	-	-
10	8	-	-	-	-	-	-
10	9	-	-	-	-	-	-
10	10	-	-	-	-	-	-
10	11				151	E14	2
10	12	70	D14	103	150	C16	2
10	13	-	-	-	149	F14	2
10	14	-	E12	102	148	F13	2
10	15	-	-	-	147	E15	2
10	16	-	E13	101	146	G13	2

Pin Descriptions (Continued)

Function Block	Macro-cell	VQ100	CP132	TQ144	PQ208	FT256	I/O Bank
11	1	-	B10	-	-	B11	2
11	2	-		-	173	D11	2
11	3	-	A10	-	174	A11	2
11	4	-	-	-	175	D10	2
11	5	-	C9	120	-	B10	2
11	6	-	-	121	-	E12	2
11	7	-	-	-	-	-	-
11	8	-	-	-	-	-	-
11	9	-	-	-	-	-	-
11	10	-	-	-	-	-	-
11	11	85	A8	124	178	F12	2
11	12	86	B8	125	179	B9	2
11	13	87	C8	126	180	C9	2
11	14	89	-	128	182	C10	2
11	15	-	-	129	183	A9	2
11	16	-	-	130	184	D9	2
12	1	-	-	-	145	F15	2
12	2	-	-	100	144	G14	2
12	3	-	-	-	143	E16	2
12	4	-	-	-	142	H12	2
12	5	-	F12	-	140	F16	2
12	6	-	F13	-	139	H16	2
12	7	-	-	-	-	-	-
12	8	-	-	-	-	-	-
12	9	-	-	-	-	-	-
12	10	-	-	-	-	-	-
12	11	68	F14	98	138	G15	2
12	12	-	G12	97	137	H13	2
12	13	67	G13	96	136	G16	2
12	14	66	-	95	135	H14	2
12	15	65	-	94	134	H15	2
12	16	-	-	-	-	J12	2

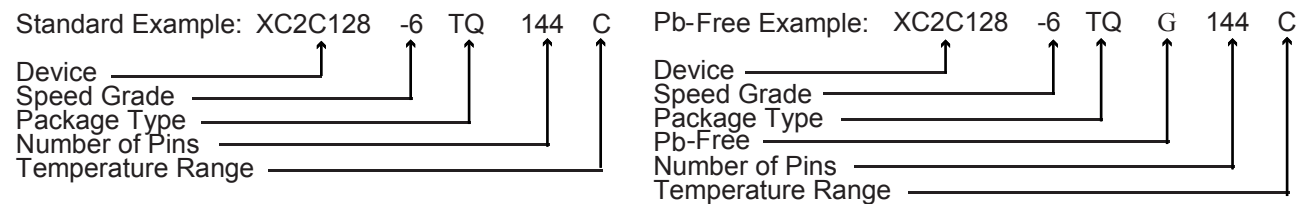
Ordering Information

Part Number	Pin/Ball Spacing	θ_{JA} (C/Watt)	θ_{JC} (C/Watt)	Package Type	Package Body Dimensions	I/O	Commercial (C) Industrial (I) ⁽¹⁾
XC2C256-6VQ100C	0.5mm	43.1	10.9	Very Thin Quad Flat Pack	14mm x 14mm	80	C
XC2C256-7VQ100C	0.5mm	43.1	10.9	Very Thin Quad Flat Pack	14mm x 14mm	80	C
XC2C256-6CP132C	0.5mm	65.0	15.0	Chip Scale Package	8mm x 8mm	106	C
XC2C256-7CP132C	0.5mm	65.0	15.0	Chip Scale Package	8mm x 8mm	106	C
XC2C256-6TQ144C	0.5mm	37.2	7.2	Thin Quad Flat Pack	20mm x 20mm	118	C
XC2C256-7TQ144C	0.5mm	37.2	7.2	Thin Quad Flat Pack	20mm x 20mm	118	C
XC2C256-6PQ208C	0.5mm	36.9	9.7	Plastic Quad Flat Pack	28mm x 28mm	173	C
XC2C256-7PQ208C	0.5mm	36.9	9.7	Plastic Quad Flat Pack	28mm x 28mm	173	C
XC2C256-6FT256C	1.0mm	34.6	6.1	Fine Pitch Thin BGA	17mm x 17mm	184	C
XC2C256-7FT256C	1.0mm	34.6	6.1	Fine Pitch Thin BGA	17mm x 17mm	184	C
XC2C256-6VQG100C	0.5mm	43.1	10.9	Very Thin Quad Flat Pack; Pb-free	14mm x 14mm	80	C
XC2C256-7VQG100C	0.5mm	43.1	10.9	Very Thin Quad Flat Pack; Pb-free	14mm x 14mm	80	C
XC2C256-6CPG132C	0.5mm	65.0	15.0	Chip Scale Package; Pb-free	8mm x 8mm	106	C
XC2C256-7CPG132C	0.5mm	65.0	15.0	Chip Scale Package; Pb-free	8mm x 8mm	106	C
XC2C256-6TQG144C	0.5mm	37.2	7.2	Thin Quad Flat Pack; Pb-free	20mm x 20mm	118	C
XC2C256-7TQG144C	0.5mm	37.2	7.2	Thin Quad Flat Pack; Pb-free	20mm x 20mm	118	C
XC2C256-6PQG208C	0.5mm	36.9	9.7	Plastic Quad Flat Pack; Pb-free	28mm x 28mm	173	C
XC2C256-7PQG208C	0.5mm	36.9	9.7	Plastic Quad Flat Pack; Pb-free	28mm x 28mm	173	C
XC2C256-6FTG256C	1.0mm	34.6	6.1	Fine Pitch Thin BGA; Pb-free	17mm x 17mm	184	C
XC2C256-7FTG256C	1.0mm	34.6	6.1	Fine Pitch Thin BGA; Pb-free	17mm x 17mm	184	C
XC2C256-7VQ100I	0.5mm	43.1	10.9	Very Thin Quad Flat Pack	14mm x 14mm	80	I
XC2C256-7CP132I	0.5mm	65.0	15.0	Chip Scale Package	8mm x 8mm	106	I
XC2C256-7TQ144I	0.5mm	37.2	7.2	Thin Quad Flat Pack	20mm x 20mm	118	I
XC2C256-7PQ208I	0.5mm	36.9	9.7	Plastic Quad Flat Pack	28mm x 28mm	173	I
XC2C256-7FT256I	1.0mm	34.6	6.1	Fine Pitch Thin BGA	17mm x 17mm	184	I

Part Number	Pin/Ball Spacing	θ_{JA} (C/Watt)	θ_{JC} (C/Watt)	Package Type	Package Body Dimensions	I/O	Commercial (C) Industrial (I) ⁽¹⁾
XC2C256-7VQG100I	0.5mm	43.1	10.9	Very Thin Quad Flat Pack; Pb-free	14mm x 14mm	80	I
XC2C256-7CPG132I	0.5mm	65.0	15.0	Chip Scale Package; Pb-free	8mm x 8mm	106	I
XC2C256-7TQG144I	0.5mm	37.2	7.2	Thin Quad Flat Pack; Pb-free	20mm x 20mm	118	I
XC2C256-7PQG208I	0.5mm	36.9	9.7	Plastic Quad Flat Pack; Pb-free	28mm x 28mm	173	I
XC2C256-7FTG256I	1.0mm	34.6	6.1	Fine Pitch Thin BGA; Pb-free	17mm x 17mm	184	I

Notes:

1. C = Commercial ($T_A = 0^\circ\text{C}$ to $+70^\circ\text{C}$); I = Industrial ($T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$).



Device Part Marking

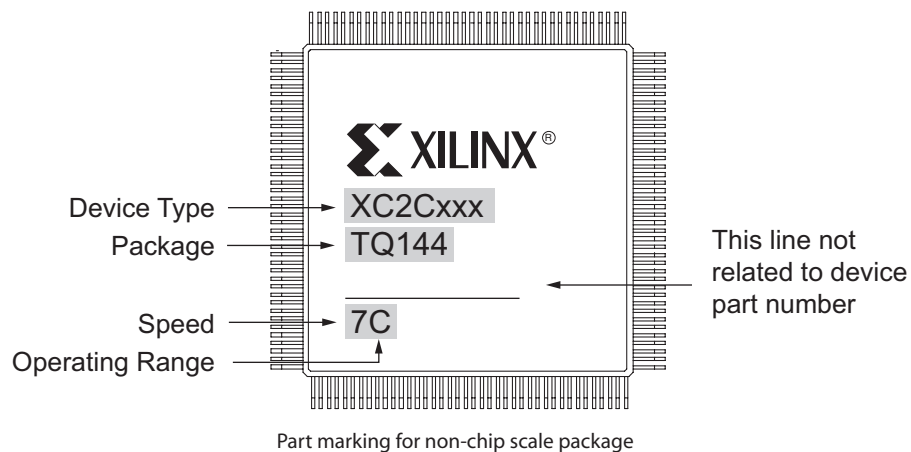
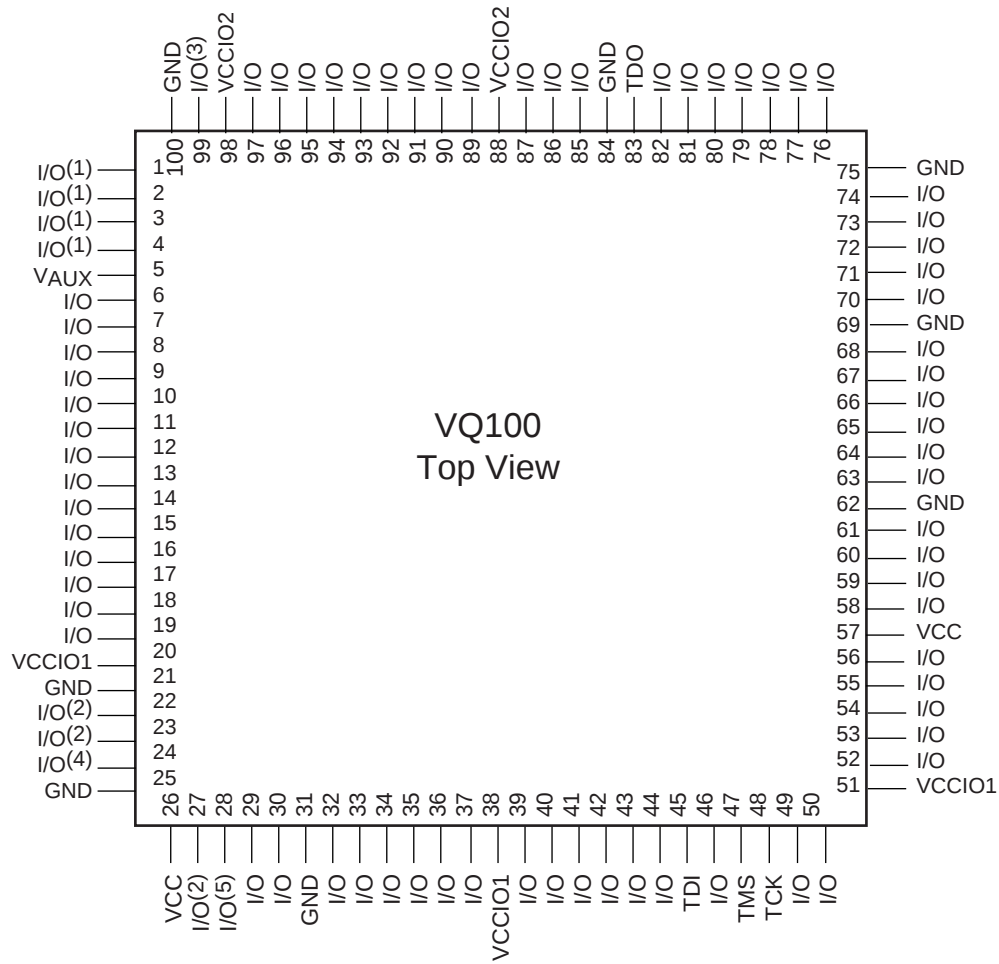


Figure 5: Sample Package with Part Marking

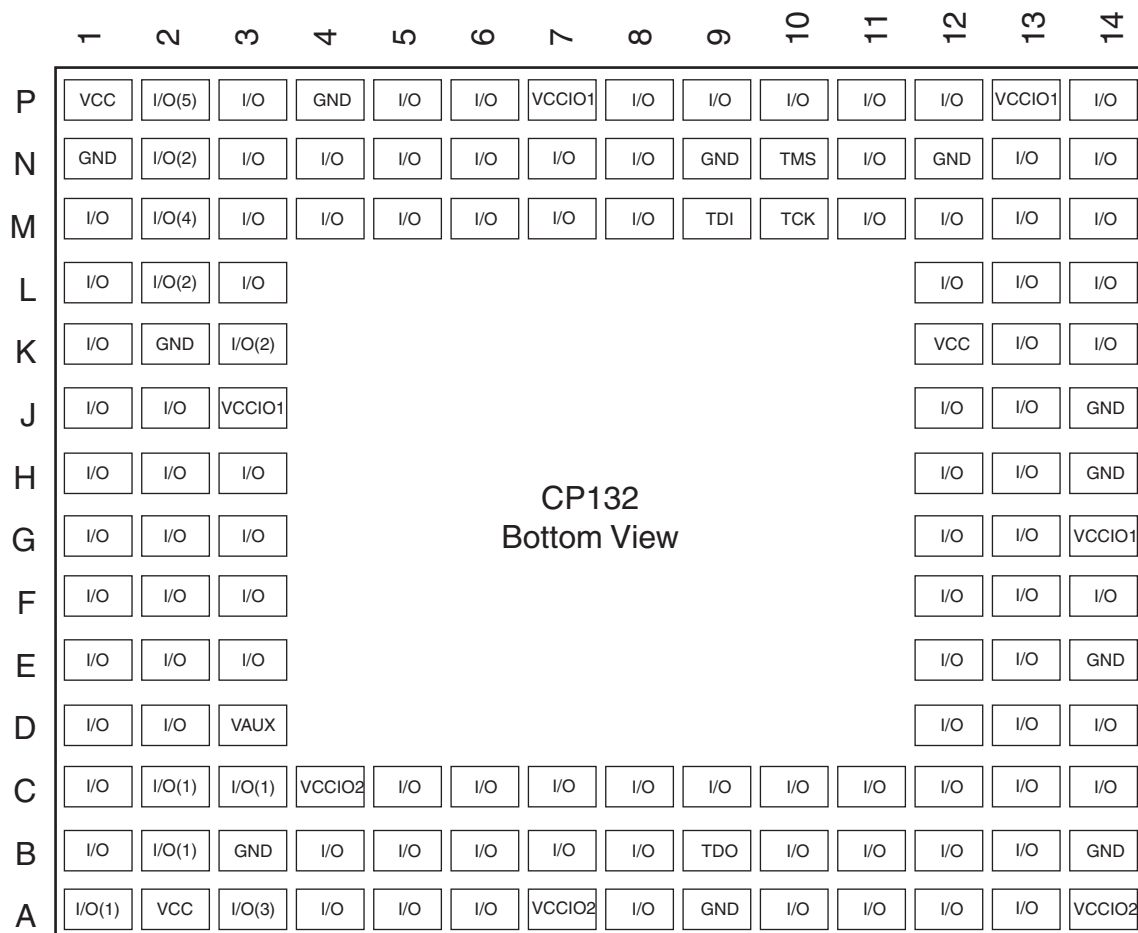
Note: Due to the small size of chip scale packages, the complete ordering part number cannot be included on the package marking. Part marking on chip scale packages by line are:

- Line 1 = X (Xilinx logo) then truncated part number
- Line 2 = Not related to device part number
- Line 3 = Not related to device part number
- Line 4 = Package code, speed, operating temperature, three digits not related to device part number. Package codes: C5 = CP132, C6 = CPG132.



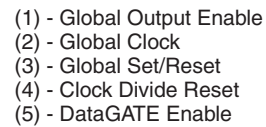
- (1) - Global Output Enable
- (2) - Global Clock
- (3) - Global Set/Reset
- (4) - Clock Divide Reset
- (5) - Data Gate

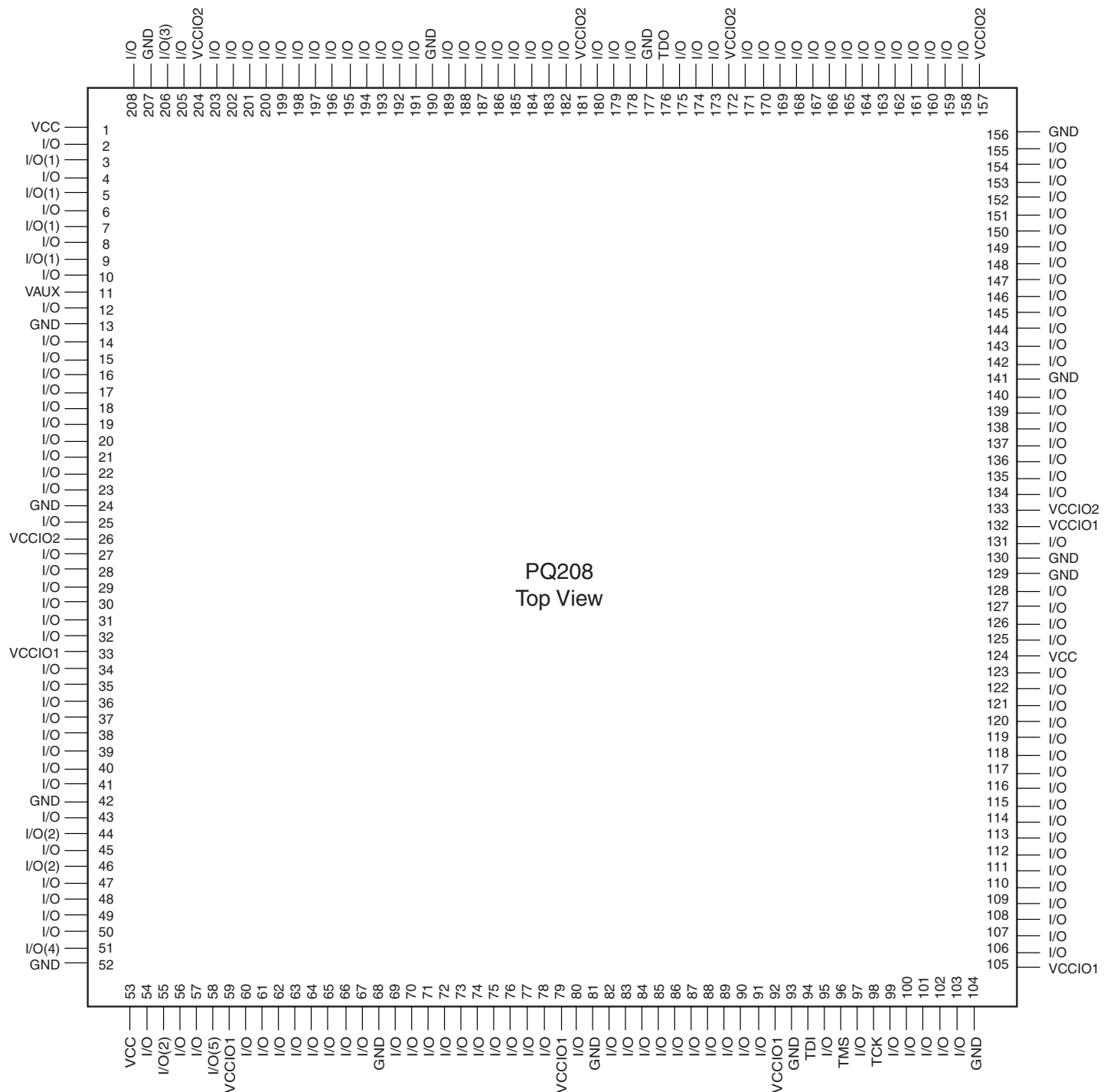
Figure 6: VQ100 Very Thin Quad Flat Pack



- (1) - Global Output Enable
- (2) - Global Clock
- (3) - Global Set/Reset
- (4) - Clock Divide Reset
- (5) - DataGATE Enable

Figure 7: CP132 Chip Scale Package





- (1) - Global Output Enable
- (2) - Global Clock
- (3) - Global Set/Reset
- (4) - Clock Divide Reset
- (5) - DataGATE Enable

Figure 9: PQ208 Quad Flat Package

	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1
A	I/O	I/O	I/O	I/O	I/O	I/O	TDO	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	NC
B	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O
C	I/O	NC	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	NC	NC	I/O(3)	I/O	NC	I/O
D	NC	I/O	NC	I/O	VCC	I/O	I/O	I/O	I/O	I/O	NC	VCC	I/O(1)	I/O(1)	I/O	NC
E	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	NC	NC	I/O(1)	I/O	I/O(1)	I/O	NC
F	I/O	I/O	I/O	I/O	I/O	GND	VCCIO2	VCCIO2	VCCIO2	VCCIO2	GND	I/O	VAUX	I/O	I/O	NC
G	I/O	I/O	I/O	I/O	NC	I/O	GND	GND	GND	GND	VCCIO2	I/O	I/O	I/O	NC	NC
H	I/O	I/O	I/O	I/O	I/O	VCCIO2	GND	GND	GND	GND	VCCIO2	I/O	I/O	I/O	I/O	I/O
J	NC	I/O	I/O	I/O	I/O	VCCIO1	GND	GND	GND	GND	VCCIO1	I/O	I/O	I/O	I/O	I/O
K	I/O	I/O	I/O	VCC	NC	VCCIO1	GND	GND	GND	GND	VCCIO1	I/O	I/O	I/O	I/O	I/O
L	I/O	I/O	I/O	I/O	I/O	GND	VCCIO1	VCCIO1	VCCIO1	VCCIO1	GND	I/O	I/O	I/O	I/O	I/O
M	I/O	I/O	I/O	I/O	I/O	I/O	NC	NC	I/O	I/O	I/O	I/O	NC	I/O(2)	I/O(2)	I/O
N	I/O	I/O	I/O	I/O	TMS	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O
P	I/O	I/O	I/O	I/O	TCK	NC	I/O	NC	I/O	I/O	I/O	I/O(2)	I/O	VCC	I/O(4)	I/O
R	I/O	I/O	I/O	I/O	I/O	TDI	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O
T	I/O	I/O	NC	NC	NC	NC	I/O	NC	I/O	I/O	I/O	I/O	I/O	I/O	I/O(5)	I/O

FT256 Bottom View

- (1) - Global Output Enable
- (2) - Global Clock
- (3) - Global Set/Reset
- (4) - Clock Divide Reset
- (5) - DataGATE Enable

Figure 10: FT256 Fine Pitch Thin BGA

Warranty Disclaimer

THESE PRODUCTS ARE SUBJECT TO THE TERMS OF THE XILINX LIMITED WARRANTY WHICH CAN BE VIEWED AT <http://www.xilinx.com/warranty.htm>. THIS LIMITED WARRANTY DOES NOT EXTEND TO ANY USE OF THE PRODUCTS IN AN APPLICATION OR ENVIRONMENT THAT IS NOT WITHIN THE SPECIFICATIONS STATED ON THE THEN-CURRENT XILINX DATA SHEET FOR THE PRODUCTS. PRODUCTS ARE NOT DESIGNED TO BE FAIL-SAFE AND ARE NOT WARRANTED FOR USE IN APPLICATIONS THAT POSE A RISK OF PHYSICAL HARM OR LOSS OF LIFE. USE OF PRODUCTS IN SUCH APPLICATIONS IS FULLY AT THE RISK OF CUSTOMER SUBJECT TO APPLICABLE LAWS AND REGULATIONS.

Additional Information

Additional information is available for the following CoolRunner-II topics:

- XAPP784: Bulletproof CPLD Design Practices
- XAPP375: Timing Model
- XAPP376: Logic Engine
- XAPP378: Advanced Features
- XAPP382: I/O Characteristics
- XAPP389: Powering CoolRunner-II
- XAPP399: Assigning VREF Pins

To access these and all application notes with their associated reference designs, click the following link and scroll down the page until you find the document you want:

[CoolRunner-II Data Sheets and Application Notes](#)

[Device Packages](#)

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
05/09/02	1.0	Initial Xilinx release.
05/13/02	1.1	Updated AC Electrical Characteristics and added new parameters.
10/31/02	1.2	Corrected package user I/O, added Voltage Referenced DC tables.
03/17/03	2.0	Added Characterization numbers for product release and device part marking
04/02/03	2.1	Updated T_{SOL} max from 260 to 220. Changed I_{CCSB} units from mA to μ A.
01/26/04	2.2	Updated Device Part Marking. Updated links and Tsol.
02/26/04	2.3	Corrected Theta JC value on XC2C256-7TQ144.
08/03/04	2.4	Pb-free documentation
08/19/04	2.5	Changes to I_{CCSB} maximum specifications in DC Electrical Characteristics table, on page 3.
10/01/04	2.6	Add Asynchronous Preset/Reset Pulse Width specification to AC Electrical Characteristics.
03/07/05	2.7	Removed -5 speed grade. Changes to Table 1, I/O Standards.
06/28/05	2.8	Move to Product Specification. Change to T_{IN25} , T_{OUT25} , T_{IN33} , and T_{OUT33} for -7 speed grade.
03/20/06	2.9	Add Warranty Disclaimer. Add note to Pin Description table that GTS, GSR and GCK pins can be used for general purpose I/O.
5/20/06	3.0	Moved T_{CONFIG} specification values from MIN column to MAX column, page 7.
02/15/07	3.1	Corrections to timing parameters t_{AOI} , t_{PSUD} , t_{PSU1} , t_{PSU2} , t_{PHD} , t_{PCO} , t_{POE} , t_{PAO} , t_{AO} , t_{SUEC} , t_{CW} , t_{CDRSU} , and f_{TOGGLE} for -6 speed grade. Corrections to t_{PSUD} , t_{CW} , and t_{CDRSU} for the -7 speed grade. Values now match the software. There were no changes to silicon or characterization. Change to V_{IH} specification for 2.5V and 1.8V LVCMOS.
03/08/07	3.2	Fixed typo in note for V_{IL} for LVCMOS18; removed note for V_{IL} for LVCMOS33.